1700V 10A SiC Schottky MPS[™] Diode

Silicon Carbide Schottky Diode



V _{RRM}	=	1700 V
I _{F (Tc = 135°C)}	=	24 A
Qc	=	53 nC

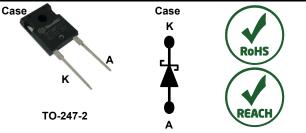
Features

- High Avalanche (UIS) Capability
- Enhanced Surge Current Capability
- Superior Figure of Merit Q_C/I_F
- Low Thermal Resistance
- 175 °C Maximum Operating Temperature
- Temperature Independent Switching Behavior
- Positive Temperature Coefficient of V_F
- Extremely Fast Switching Speeds

Advantages

- Low Standby Power Losses
- Improved Circuit Efficiency (Lower Overall Cost)
- Low Switching Losses
- Ease of Paralleling without Thermal Runaway
- Smaller Heat Sink Requirements
- Low Reverse Recovery Current
- Low Device Capacitance
- Low Reverse Leakage Current





Applications

- Boost Diode in Power Factor Correction (PFC)
- Switched Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Motor Drives
- Freewheeling / Anti-parallel Diode in Inverters
- Solar Inverters & Wind Energy Converters
- Electric Vehicles (EV) & DC Fast Charging
- Induction Heating & Welding

Absolute Maximum Ratings (At T_c = 25 °C Unless Otherwise Stated)

Parameter	Symbol	Conditions	Values	Unit	
Repetitive Peak Reverse Voltage	V _{RRM}		1700	V	
		T _C = 25 °C, D = 1	49		
Continuous Forward Current	I _F	T _C = 135 °C, D = 1	24	А	
		T _C = 166 °C, D = 1	10		
Non-Repetitive Peak Forward Surge Current, Half Sine Wave		T _C = 25 °C, t _P = 10 ms	112	А	
	I _{F,SM}	T _C = 150 °C, t _P = 10 ms	84		
Repetitive Peak Forward Surge Current, Half Sine Wave	I	T _C = 25 °C, t _P = 10 ms	67	٨	
	I _{F,RM}	T _C = 150 °C, t _P = 10 ms	48	A	
Non-Repetitive Peak Forward Surge Current	I _{F,max}	T _C = 25 °C, t _P = 10 μs	560	А	
i ² t Value	∫i ² dt	T _C = 25 °C, t _P = 10 ms	63	A ² s	
Non-Repetitive Avalanche Energy	E _{AS}	L = 5.6 mH, I _{AS} = 10 A	280	mJ	
Diode Ruggedness	dV/dt	V _R = 0 ~ 1360 V	200	V/ns	
Power Dissipation	P _{tot}	T _C = 25 °C	349	W	
Operating and Storage Temperature	T_{j} , T_{stg}		-55 to 175	°C	

1700V	10A	SiC	Schottky	/ MPS™	Diode
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Electrical Characteristics

Devemeter	Sympol	Conditions		Values		11	
Parameter	Symbol			Min.	Тур.	Max.	Unit
Diode Forward Voltage	V	I _F = 10 A, T _j = 25 °C			1.5	1.8	V
	V _F	I _F = 10 A, T _j = 175 °C			2	2.4	
Reverse Current	I	V _R = 1700 V, T _j = 25 °C		2	10	μA	
	I _R	V_{R} = 1700 V, T _j = 175 °C		60	300		
Total Capacitive Charge	0	V _R = 600 V			38		nC
	Q _C	I _F ≤ I _{F,MAX} dI _F /dt = 200 A/µs	V _R = 1200 V		53		nc
Switching Time	+	$T_j = 175 °C$	V _R = 600 V		< 10		ns
	t _s	V _R = 1200 V			< 10		115
Total Capacitance	С	V _R = 1 V, f = 1 MHz		988		ηĘ	
	C	V _R = 1200 V, f = 1 MHz			53		pF

Thermal / Mechanical Characteristics

Thermal Resistance, Junction - Case	R _{thJC}		0.43	°C/W
Weight	W _T		6	g
Mounting Torque	T _M	M3 Screw	1.1	Nm





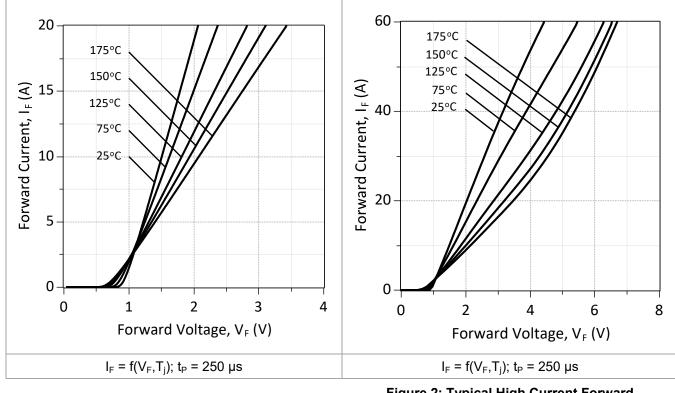
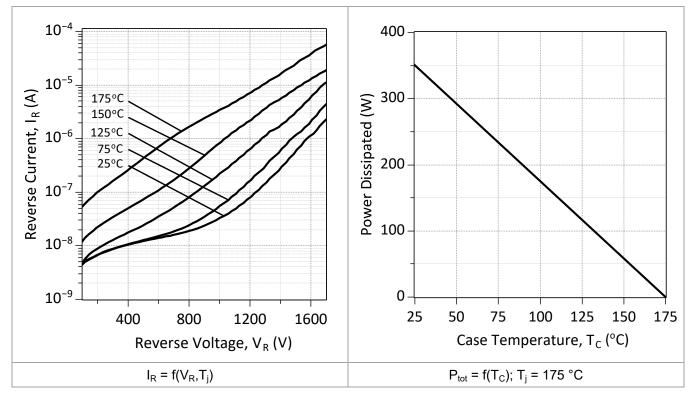


Figure 1: Typical Forward Characteristics

Figure 2: Typical High Current Forward Characteristics



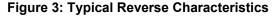
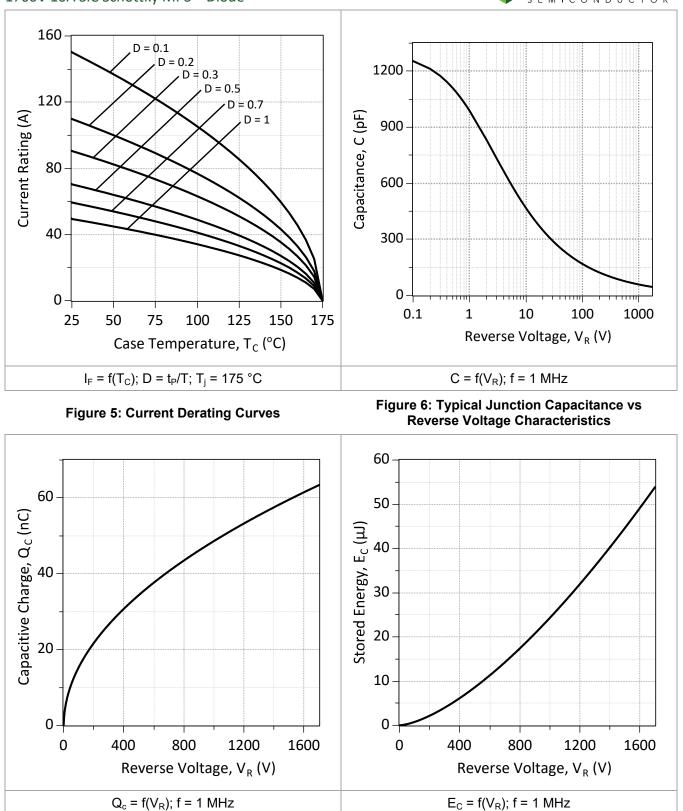
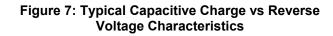


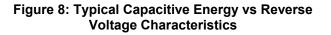
Figure 4: Power Derating Curve

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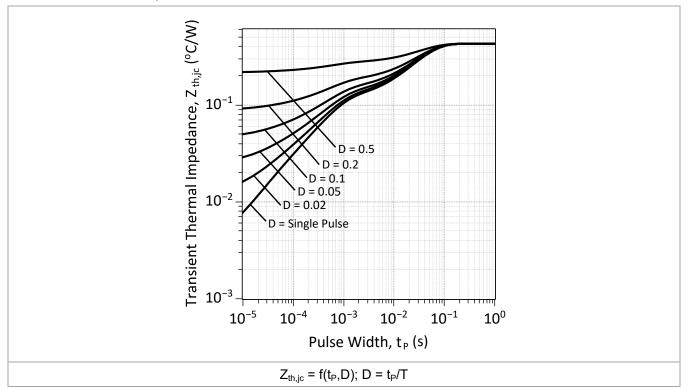




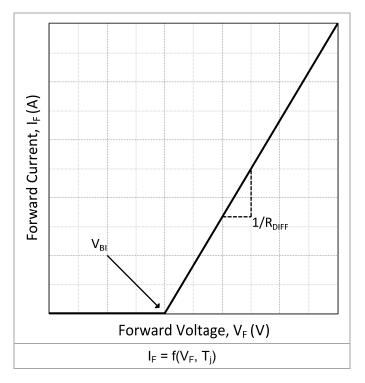




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 $I_{F} = (V_{F} - V_{BI})/R_{DIFF} (A)$

Built-In Voltage (V_{BI}):

$$V_{BI}(T_j) = m^*T_j + n (V),$$

m = -1.42e-03, n = 0.986

Differential Resistance (R_{DIFF}):

$$R_{DIFF}(T_j) = a^*T_j^2 + b^*T_j + c(\Omega);$$

CTOF

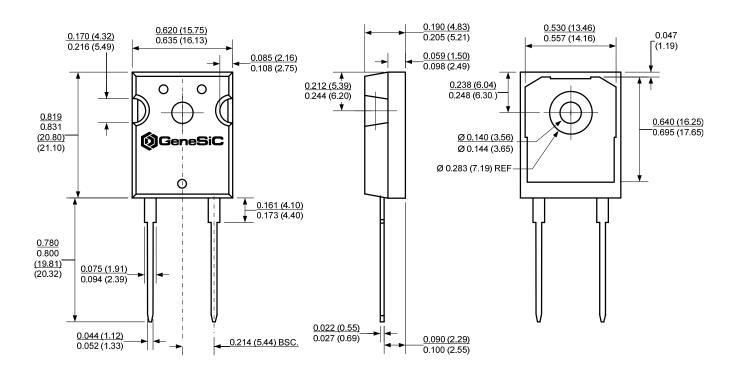
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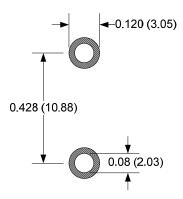
Package Dimensions

TO-247-2

Package Outline



Recommended Solder Pad Layout



NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

GB10MPS17-247 1700V 10A SiC Schottky MPS[™] Diode



RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS 2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863. RoHS Declarations for this product can be obtained from your GeneSiC representative.

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REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

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Related Links

- SPICE Models: https://www.genesicsemi.com/schottky-mps
- Evaluation Boards: https://www.genesicsemi.com/technical-support
- Quality Manual: https://www.genesicsemi.com/technical-support/quality-manual
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